ICS9DB104
(Not recommended for new designs)

Four Output Differential Buffer for PCI-Express

Recommended Application:

DB400 Intel Yellow Cover part with PCI-Express support.

Output Features:

- 4 - 0.7V current-mode differential output pairs
- Supports zero delay buffer mode and fanout mode
- Bandwidth programming available

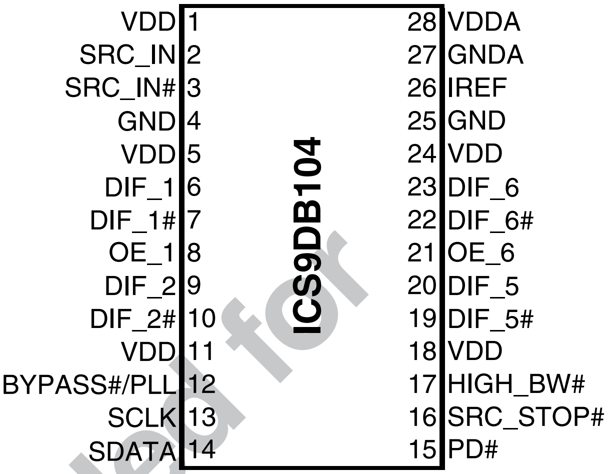
Key Specifications:

- Outputs cycle-cycle jitter: < 50ps
- Outputs skew: < 50ps
- +/- 300ppm frequency accuracy on output clocks

Features/Benefits:

- Supports tight ppm accuracy clocks for Serial-ATA
- Spread spectrum modulation tolerant, 0 to -0.5% down spread and +/- 0.25% center spread
- Supports undriven differential output pair in PD# and SRC_STOP# for power management.

Pin Configuration



Pin name	Pin	Pin	Pin name
VDD	1	28	VDDA
SRC_IN	2	27	GNDA
SRC_IN#	3	26	IREF
GND	4	25	GND
VDD	5	24	VDD
DIF_1	6	23	DIF_6
DIF_1#	7	22	DIF_6#
OE_1	8	21	OE_6
DIF_2	9	20	DIF_5
DIF_2#	10	19	DIF_5#
VDD	11	18	VDD
BYPASS#/PLL	12	17	HIGH_BW#
SCLK	13	16	SRC_STOP#
SDATA	14	15	PD#

28-pin SSOP & TSSOP

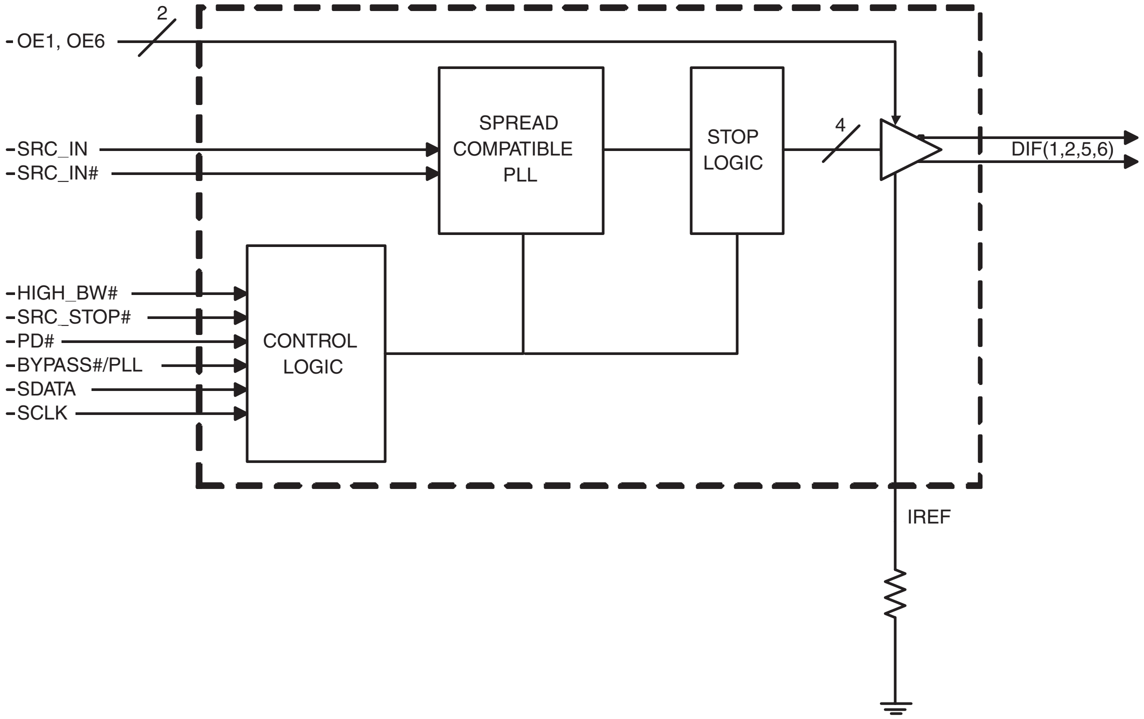
Pin Description

PIN #	PIN NAME	PIN TYPE	DESCRIPTION
1	VDD	PWR	Power supply, nominal 3.3V
2	SRC_IN	IN	0.7 V Differential SRC TRUE input
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input
4	GND	PWR	Ground pin.
5	VDD	PWR	Power supply, nominal 3.3V
6	DIF_1	OUT	0.7V differential true clock outputs
7	DIF_1#	OUT	0.7V differential complement clock outputs
8	OE_1	IN	Active high input for enabling outputs. 0 = tri-state outputs, 1= enable outputs
9	DIF_2	OUT	0.7V differential true clock outputs
10	DIF_2#	OUT	0.7V differential complement clock outputs
11	VDD	PWR	Power supply, nominal 3.3V
12	BYPASS#/PLL	IN	Input to select Bypass(fan-out) or PLL (ZDB) mode 0 = Bypass mode, 1= PLL mode
13	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.
14	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.
15	PD#	IN	Asynchronous active low input pin used to power down the device. The internal clocks are disabled and the VCO and the crystal are stopped.
16	SRC_STOP#	IN	Active low input to stop diff outputs.
17	HIGH_BW#	IN	3.3V input for selecting PLL Band Width 0 = High, 1= Low
18	VDD	PWR	Power supply, nominal 3.3V
19	DIF_5#	OUT	0.7V differential complement clock outputs
20	DIF_5	OUT	0.7V differential true clock outputs
21	OE_6	IN	Active high input for enabling outputs. 0 = tri-state outputs, 1= enable outputs
22	DIF_6#	OUT	0.7V differential complement clock outputs
23	DIF_6	OUT	0.7V differential true clock outputs
24	VDD	PWR	Power supply, nominal 3.3V
25	GND	PWR	Ground pin.
26	IREF	OUT	This pin establishes the reference current for the differential current-mode output pairs. This pin requires a fixed precision resistor tied to ground in order to establish the appropriate current. 475 ohms is the standard value.
27	GNDA	PWR	Ground pin for the PLL core.
28	VDDA	PWR	3.3V power for the PLL core.

General Description

ICS9DB104 follows the Intel DB400 Differential Buffer Specification. This buffer provides four SRC clocks for PCI-Express, next generation I/O devices. **ICS9DB104** is driven by a differential input pair from a CK409/CK410 main clock generator, such as the ICS952601 or ICS954101. **ICS9DB104** can run at speeds up to 200MHz. It provides ouputs meeting tight cycle-to-cycle jitter (50ps) and output-to-output skew (50ps) requirements.

Block Diagram



Power Groups

Pin Number		Description
VDD	GND	
1	4	SRC_IN/SRC_IN#
5,11,18,24	4,25	DIF Outputs
28	27	IREF
28	27	Analog VDD & GND for PLL core

Absolute Max

Symbol	Parameter	Min	Max	Units
VDD_A	3.3V Core Supply Voltage		4.6	V
VDD_In	3.3V Logic Supply Voltage		4.6	V
V_{IL}	Input Low Voltage	GND-0.5		V
V_{IH}	Input High Voltage		V_{DD}+0.5V	V
Ts	Storage Temperature	-65	150	°C
Tambient	Ambient Operating Temp	0	70	°C
Tcase	Case Temperature		115	°C
ESD prot	Input ESD protection human body model	2000		V

Electrical Characteristics - Input/Supply/Common Output Parameters

T_A = 0 - 70°C; Supply Voltage V_{DD} = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage	V_{IH}	3.3 V +/-5%	2		V_{DD} + 0.3	V	
Input Low Voltage	V_{IL}	3.3 V +/-5%	GND - 0.3		0.8	V	
Input High Current	I_{IH}	$V_{IN} = V_{DD}$	-5		5	uA	
Input Low Current	I_{IL1}	V_{IN} = 0 V; Inputs with no pull-up resistors	-5			uA	
	I_{IL2}	V_{IN} = 0 V; Inputs with pull-up resistors	-200			uA	
Operating Supply Current	$I_{DD3.3OP}$	Full Active, C_L = Full load;			200	mA	
Powerdown Current	$I_{DD3.3PD}$	all diff pairs driven			40	mA	
		all differential pairs tri-stated			12	mA	
Input Frequency[3]	F_i	V_{DD} = 3.3 V	80	100/133 166/200	220	MHz	3
Pin Inductance[1]	L_{pin}				7	nH	1
Input Capacitance[1]	C_{IN}	Logic Inputs	1.5		5	pF	1
	C_{OUT}	Output pin capacitance			6	pF	1
PLL Bandwidth	BW	PLL Bandwidth when PLL_BW=0		4		MHz	1
		PLL Bandwidth when PLL_BW=1		2		MHz	1
Clk Stabilization[1,2]	T_{STAB}	From V_{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1	ms	1,2
Modulation Frequency		Triangular Modulation	30		33	kHz	1
Tdrive_SRC_STOP#		DIF output enable after SRC_Stop# de-assertion			10	ns	1,3
Tdrive_PD#		DIF output enable after PD# de-assertion			300	us	1,3
Tfall		Fall time of PD# and SRC_STOP#			5	ns	1
Trise		Rise time of PD# and SRC_STOP#			5	ns	2

[1] Guaranteed by design and characterization, not 100% tested in production.

[2] See timing diagrams for timing requirements.

[3] Time from deassertion until outputs are >200 mV

Electrical Characteristics - DIF 0.7V Current Mode Differential Pair

T_A = 0 - 70°C; V_{DD} = 3.3 V +/-5%; C_L =2pF, R_S=33.2Ω, R_P=49.9Ω, I_{REF} = 475Ω

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Zo^1	$V_O = V_x$	3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended signal using oscilloscope math function.	660		850	mV	1,3
Voltage Low	VLow		-150		150		1,3
Max Voltage	Vovs	Measurement on single ended signal using absolute value.			1150	mV	1
Min Voltage	Vuds		-300				1
Crossing Voltage (abs)	Vcross(abs)		250		550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges			140	mV	1
Long Accuracy	ppm	see Tperiod min-max values			0	ppm	1,2
Average period	Tperiod	200MHz nominal	4.9985		5.0015	ns	2
		200MHz spread	4.9985		5.0266	ns	2
		166.66MHz nominal	5.9982		6.0018	ns	2
		166.66MHz spread	5.9982		6.0320	ns	2
		133.33MHz nominal	7.4978		7.5023	ns	2
		133.33MHz spread	7.4978		5.4000	ns	2
		100.00MHz nominal	9.9970		10.0030	ns	2
		100.00MHz spread	9.9970		10.0533	ns	2
Absolute min period	T_{absmin}	200MHz nominal	4.8735			ns	1,2
		166.66MHz nominal/spread	5.8732			ns	1,2
		133.33MHz nominal/spread	7.3728			ns	1,2
		100.00MHz nominal/spread	9.8720			ns	1,2
Rise Time	t_r	V_{OL} = 0.175V, V_{OH} = 0.525V	175		700	ps	1
Fall Time	t_f	V_{OH} = 0.525V V_{OL} = 0.175V	175		700	ps	1
Rise Time Variation	d-t_r				125	ps	1
Fall Time Variation	d-t_f				125	ps	1
Duty Cycle	d_{t3}	Measurement from differential wavefrom	45		55	%	1
Skew	t_{sk3}	V_T = 50%			50	ps	1
Jitter, Cycle to cycle	$t_{jcyc-cyc}$	PLL mode, Measurement from differential wavefrom			50	ps	1
		BYPASS mode as additive jitter			50	ps	1

[1] Guaranteed by design and characterization, not 100% tested in production.

[2] All Long Term Accuracy and Clock Period specifications are guaranteed with the assumption that the input clock complies with CK409/CK410 accuracy requirements

[3] $I_{REF} = V_{DD}/(3xR_R)$. For R_R = 475Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O=50Ω.

General SMBus serial interface information for the ICS9DB104

How to Write:

- Controller (host) sends a start bit.
- Controller (host) sends the write address DC $_{(h)}$
- ICS clock will ***acknowledge***
- Controller (host) sends the begining byte location = N
- ICS clock will ***acknowledge***
- Controller (host) sends the data byte count = X
- ICS clock will ***acknowledge***
- Controller (host) starts sending ***Byte N through Byte N + X -1***
- ICS clock will ***acknowledge*** each byte ***one at a time***
- Controller (host) sends a Stop bit

Index Block Write Operation			
Controller (Host)			**ICS (Slave/Receiver)**
T	starT bit		
Slave Address $DC_{(h)}$			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
Data Byte Count = X			
			ACK
Beginning Byte N		X Byte	
			ACK
○			
○			○
○			○
			○
Byte N + X - 1			
			ACK
P	stoP bit		

How to Read:

- Controller (host) will send start bit.
- Controller (host) sends the write address DC $_{(h)}$
- ICS clock will ***acknowledge***
- Controller (host) sends the begining byte location = N
- ICS clock will ***acknowledge***
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address DD $_{(h)}$
- ICS clock will ***acknowledge***
- ICS clock will send the data byte count = X
- ICS clock sends ***Byte N + X -1***
- ICS clock sends ***Byte 0 through byte X (if X*** $_{(h)}$ ***was written to byte 8)***.
- Controller (host) will need to acknowledge each byte
- Controllor (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation			
Controller (Host)		**ICS (Slave/Receiver)**	
T	starT bit		
Slave Address $DC_{(h)}$			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
RT	Repeat starT		
Slave Address $DD_{(h)}$			
RD	ReaD		
			ACK
			Data Byte Count = X
ACK			
		X Byte	Beginning Byte N
ACK			
			○
○			○
○			○
○			
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

SMBus Table: Frequency Select Register, READ/WRITE ADDRESS (DC/DD)

Byte 0	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	PD# drive mode		RW	driven	Hi-Z	0
Bit 6	-	SRC_Stop# drive		RW	driven	Hi-Z	0
Bit 5	-	Reserved		RW	Reserved		X
Bit 4	-	Reserved		RW	Reserved		X
Bit 3	-	Reserved		RW	Reserved		X
Bit 2	-	PLL_BW# adjust		RW	High BW	Low BW	1
Bit 1	-	BYPASS#/PLL		RW	fan-out	ZDB	1
Bit 0	-	SRC_DIV#		RW	div /2	x1	1

SMBus Table: Output Control Register

Byte 1	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	Reserved		RW	User should write '0' to minimize power		1
Bit 6	23,22	DIF_6	Output Control	RW	Disable	Enable	1
Bit 5	20,19	DIF_5	Output Control	RW	Disable	Enable	1
Bit 4	-	Reserved		RW	User should write '0' to minimize power		1
Bit 3	-	Reserved		RW	User should write '0' to minimize power		1
Bit 2	9,10	DIF_2	Output Control	RW	Disable	Enable	1
Bit 1	6,7	DIF_1	Output Control	RW	Disable	Enable	1
Bit 0	-	Reserved		RW	User should write '0' to minimize power		1

SMBus Table: Output Control Register

Byte 2	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	Reserved		RW	Reserved		0
Bit 6	23,22	DIF_6	Output Control	RW	Free-run	Stoppable	0
Bit 5	20,19	DIF_5	Output Control	RW	Free-run	Stoppable	0
Bit 4	-	Reserved		RW	Reserved		0
Bit 3	-	Reserved		RW	Reserved		0
Bit 2	9,10	DIF_2	Output Control	RW	Free-run	Stoppable	0
Bit 1	6,7	DIF_1	Output Control	RW	Free-run	Stoppable	0
Bit 0	-	Reserved		RW	Reserved		0

SMBus Table: Output Control Register

Byte 3	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7		Reserved		RW	Reserved		X
Bit 6		Reserved		RW	Reserved		X
Bit 5		Reserved		RW	Reserved		X
Bit 4		Reserved		RW	Reserved		X
Bit 3		Reserved		RW	Reserved		X
Bit 2		Reserved		RW	Reserved		X
Bit 1		Reserved		RW	Reserved		X
Bit 0		Reserved		RW	Reserved		X

SMBus Table: Vendor & Revision ID Register

Byte 4	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	RID3	REVISION ID	R	-	-	X
Bit 6	-	RID2		R	-	-	X
Bit 5	-	RID1		R	-	-	X
Bit 4	-	RID0		R	-	-	X
Bit 3	-	VID3	VENDOR ID	R	-	-	0
Bit 2	-	VID2		R	-	-	0
Bit 1	-	VID1		R	-	-	0
Bit 0	-	VID0		R	-	-	1

SMBus Table: DEVICE ID

Byte 5	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	Device ID 7 (MSB)		RW	Reserved		0
Bit 6	-	Device ID 6		RW	Reserved		0
Bit 5	-	Device ID 5		RW	Reserved		0
Bit 4	-	Device ID 4		RW	Reserved		0
Bit 3	-	Device ID 3		RW	Reserved		1
Bit 2	-	Device ID 2		RW	Reserved		0
Bit 1	-	Device ID 1		RW	Reserved		0
Bit 0	-	Device ID 0		RW	Reserved		0

SMBus Table: Byte Count Register

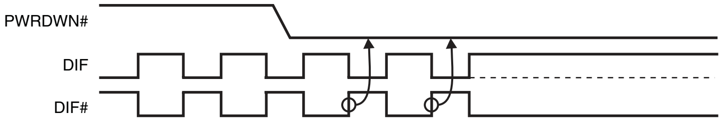
Byte 6	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	BC7	Writing to this register configures how many bytes will be read back.	RW	-	-	0
Bit 6	-	BC6		RW	-	-	0
Bit 5	-	BC5		RW	-	-	0
Bit 4	-	BC4		RW	-	-	0
Bit 3	-	BC3		RW	-	-	0
Bit 2	-	BC2		RW	-	-	1
Bit 1	-	BC1		RW	-	-	0
Bit 0	-	BC0		RW	-	-	1

PD#

The PD# pin cleanly shuts off all clocks and places the device into a power saving mode. PD# must be asserted before shutting off the input clock or power to insure an orderly shutdown. PD is asynchronous active-low input for both powering down the device and powering up the device. When PD# is asserted, all clocks will be driven high, or tri-stated (depending on the PD# drive mode and Output control bits) before the PLL is shut down.

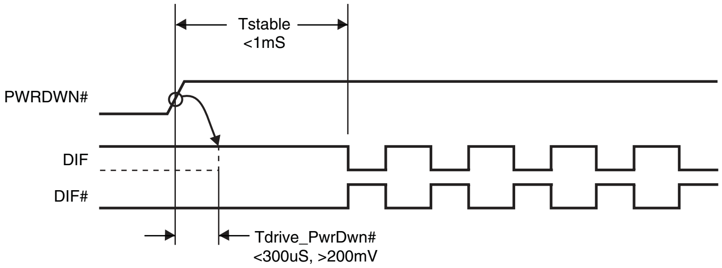
PD# Assertion

When PD# is sampled low by two consecutive rising edges of DIF#, all DIF outputs must be held High, or tri-stated (depending on the PD# drive mode and Output control bits) on the next High-Low transition of the DIF# outputs. When the PD# drive mode bit is set to ‘0’, all clock outputs will be held with DIF driven High with 2 x I_{REF} and DIF# tri-stated. If the PD# drive mode bit is set to ‘1’, both DIF and DIF# are tri-stated.



PD# De-assertion

Power-up latency is less than 1 ms. This is the time from de-assertion of the PD# pin, or VDD reaching 3.3V, or the time from valid SRC_IN clocks until the time that stable clocks are output from the device (PLL Locked). If the PD# drive mode bit is set to ‘1’, all the DIF outputs must driven to a voltage of >200 mV within 300 ms of PD# de-assertion.



SRC_STOP#

The SRC_STOP# signal is an active-low asynchronous input that cleanly stops and starts the DIF outputs. A valid clock must be present on SRC_IN for this input to work properly. The SRC_STOP# signal is de-bounced and must remain stable for two consecutive rising edges of DIF# to be recognized as a valid assertion or de-assertion.

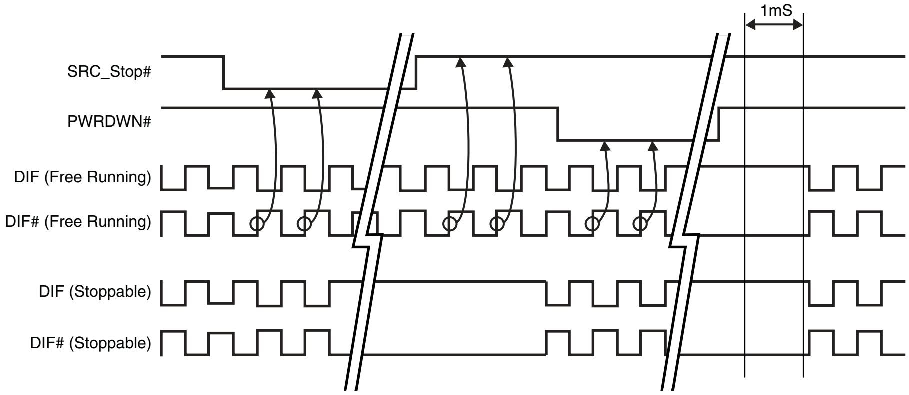
SRC_STOP# - Assertion (transition from '1' to '0')

Asserting SRC_STOP# causes all DIF outputs to stop after their next transition (if the control register settings allow the output to stop). When the SRC_STOP# drive bit is '0', the final state of all stopped DIF outputs is DIF = High and DIF# = Low. There is no change in output drive current. DIF is driven with $6xI_{REF.}$ DIF# is not driven, but pulled low by the termination. When the SRC_STOP# drive bit is '1', the final state of all DIF output pins is Low. Both DIF and DIF# are not driven.

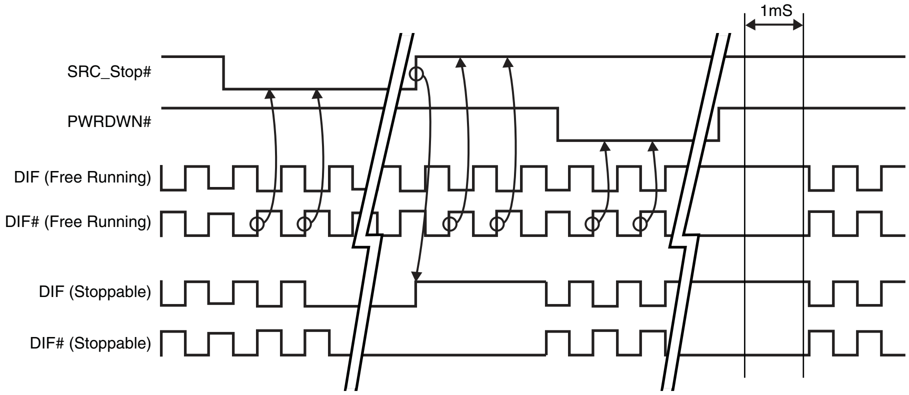
SRC_STOP# - De-assertion (transition from '0' to '1')

All stopped differential outputs resume normal operation in a glitch-free manner. The de-assertion latency to active outputs is 2-6 DIF clock periods, with all DIF outputs resuming simultaneously. If the SRC_STOP# drive control bit is '1' (tri-state), all stopped DIF outputs must be driven High (>200 mV) within 10 ns of de-assertion.

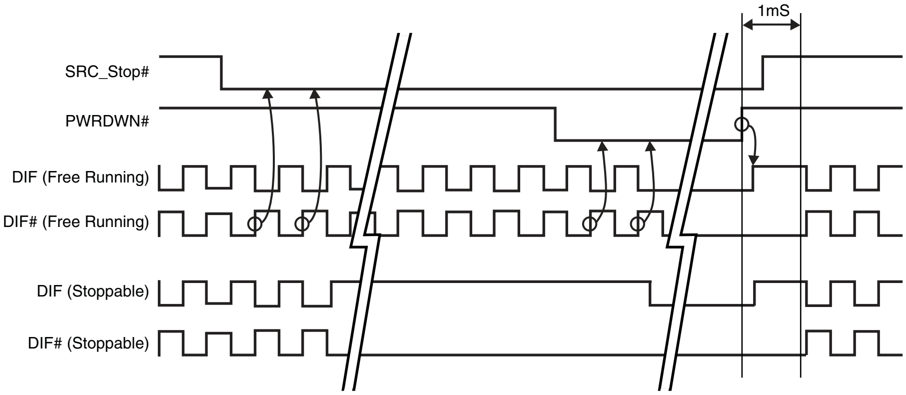
SRC_STOP_1 (SRC_Stop = Driven, PD = Driven)



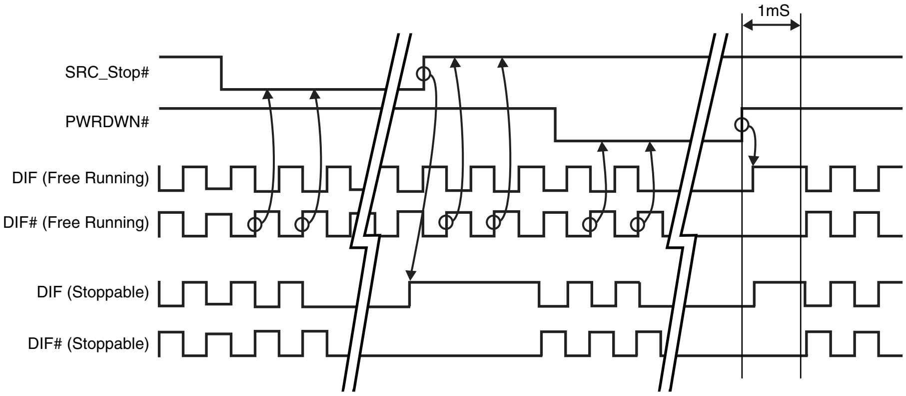
SRC_STOP_2 (SRC_Stop =Tristate, PD = Driven)

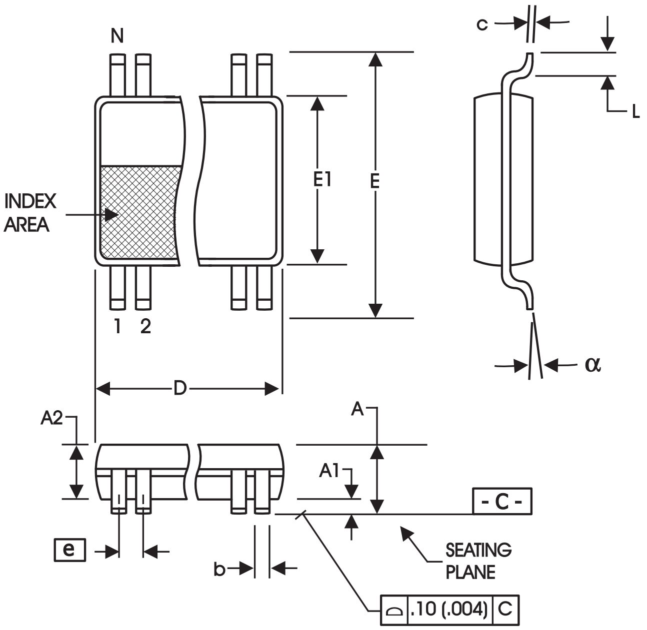


SRC_STOP_3 (SRC_Stop = Driven, PD = Tristate)



SRC_STOP_4 (SRC_Stop = Tristate, PD = Tristate)





209 mil SSOP

SYMBOL	In Millimeters COMMON DIMENSIONS		In Inches COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	--	2.00	--	.079
A1	0.05	--	.002	--
A2	1.65	1.85	.065	.073
b	0.22	0.38	.009	.015
c	0.09	0.25	.0035	.010
D	SEE VARIATIONS		SEE VARIATIONS	
E	7.40	8.20	.291	.323
E1	5.00	5.60	.197	.220
e	0.65 BASIC		0.0256 BASIC	
L	0.55	0.95	.022	.037
N	SEE VARIATIONS		SEE VARIATIONS	
α	0°	8°	0°	8°

VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
28	9.90	10.50	.390	.413

Reference Doc.: JEDEC Publication 95, MO-150

10-0033

Ordering Information

ICS9DB104yFLxT

Example:

ICS XXXX y F Lx T

Designation for tape and reel packaging

LF or LN =

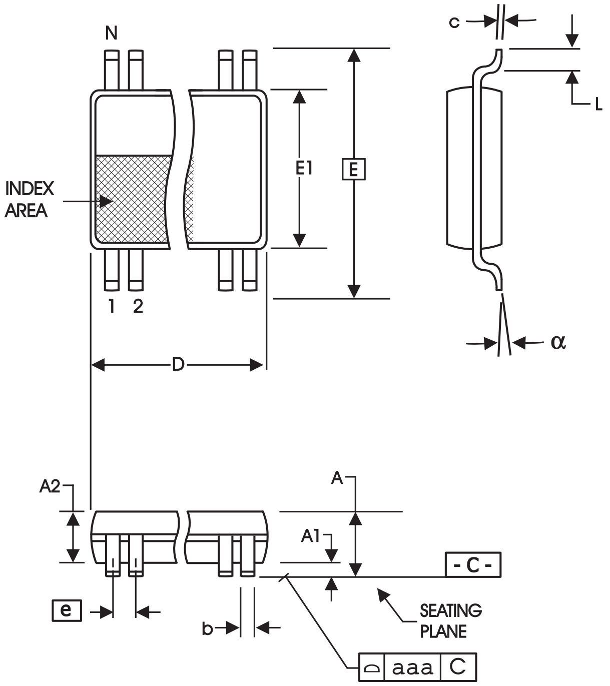
Lead Free, RoHS Compliant (Optional)

Package Type
F = SSOP

Revision Designator (will not correlate with datasheet revision)

Device Type (consists of 3 to 7 digit numbers)

Prefix
ICS = Standard Device



4.40 mm. Body, 0.65 mm. Pitch TSSOP

(173 mil) (25.6 mil)

SYMBOL	In Millimeters COMMON DIMENSIONS		In Inches COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	--	1.20	--	.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.19	0.30	.007	.012
c	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	.169	.177
e	0.65 BASIC		0.0256 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
a	0°	8°	0°	8°
aaa	--	0.10	--	.004

VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
28	9.60	9.80	.378	.386

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

Ordering Information

ICS9DB104yGLxT

Example:

ICS XXXX y G Lx T

- **T** — **Designation for tape and reel packaging**
- **Lx** — **LF or LN =**
  Lead Free, RoHS Compliant (Optional)
- **G** — **Package Type**
  G = TSSOP
- **y** — **Revision Designator** (will not correlate with datasheet revision)
- **XXXX** — **Device Type (consists of 3 to 7 digit numbers)**
- **ICS** — **Prefix**
  ICS = Standard Device

Revision History

Rev.	Issue Date	Description	Page #
D	10/26/05	Updated LF Ordering Information to LN or LF.	12, 13
E	12/14/07	Updated SMBus serial Interface Information.	6

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
   "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
   "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.
   Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.
6. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
7. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
9. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
10. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
11. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.

(Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.

(Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.4.0-1 November 2017)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

© 2020 Renesas Electronics Corporation. All rights reserved.